

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1028	solder with (tin or SN) with (Ag or silver) and lead adj free	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/08/17 17:34
L2	154	solder with (tin or SN) with (Ag or silver) and lead adj free and solder with bump and eutectic and reflow	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/08/17 17:32
L3	43	solder with (tin or SN) with (Ag or silver) and lead adj free and solder with bump and eutectic and reflow and (plate or plating or plated) with reflow\$3	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/08/17 17:33
L4	1294	(257/737).CCLS.	USPAT	OR	OFF	2005/08/17 17:34
L5	16	I1 and I4	USPAT	OR	OFF	2005/08/17 17:34
L6	1028	solder with (tin or SN) with (Ag or silver) and lead adj free	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/08/17 17:34
L7	4605	((257/738) or (257/737) or (257/778)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/17 17:35
L8	34	I6 and I7	USPAT	OR	OFF	2005/08/17 17:35
L9	69	I6 and I7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 17:35